

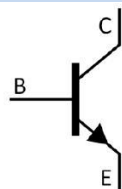
/ Descriptions

SOT-23 NPN

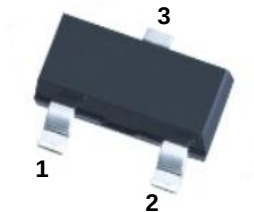
/ Features

/ Applications

/ Equivalent Circuit

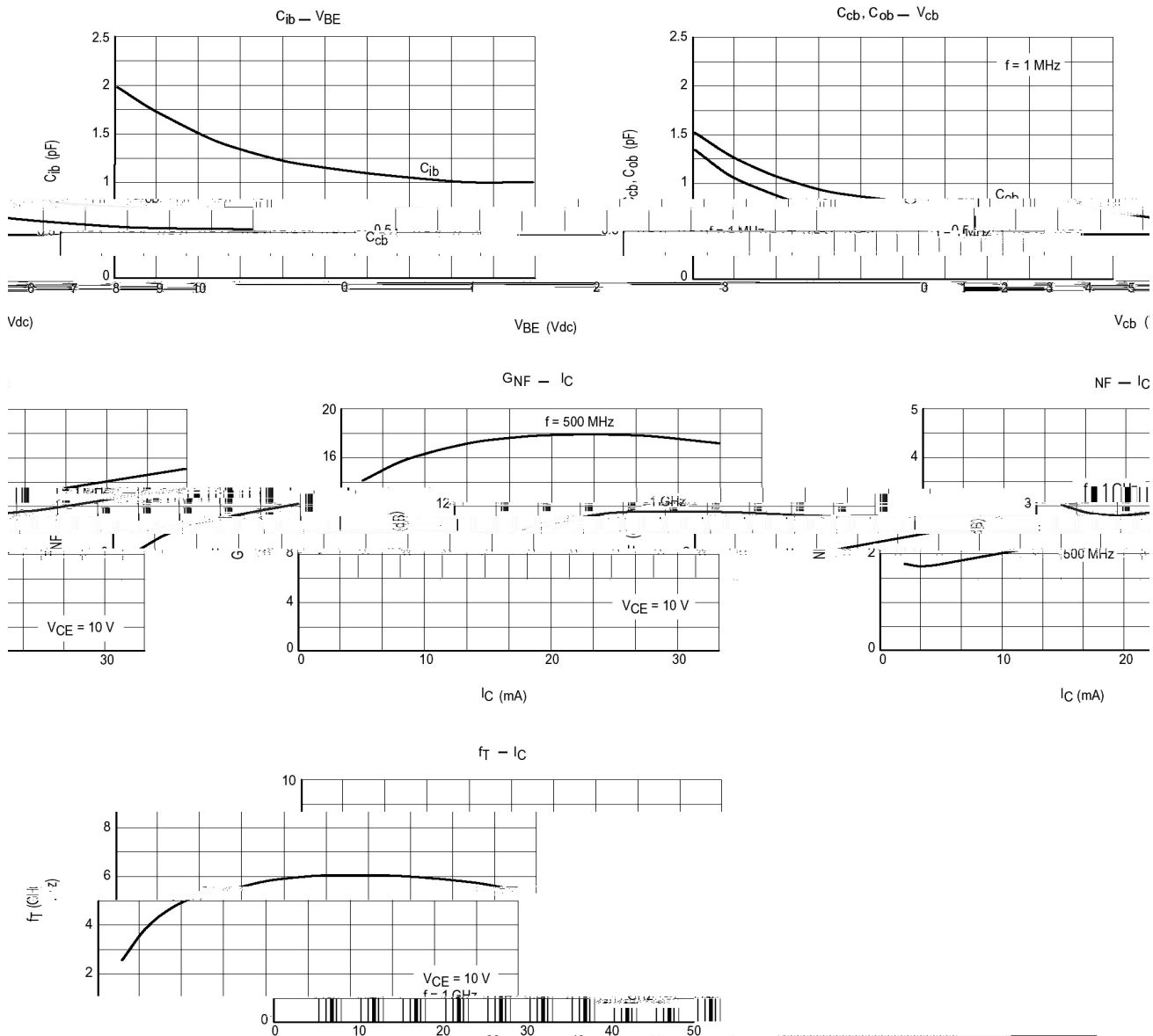


/ Pinning



/ h_{FE} Classifications & Marking

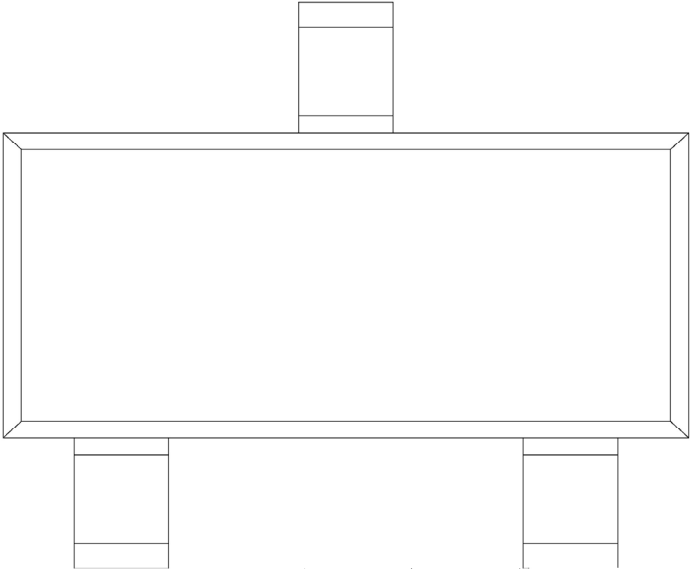
/ Electrical Characteristic Curve



/ Package Dimensions



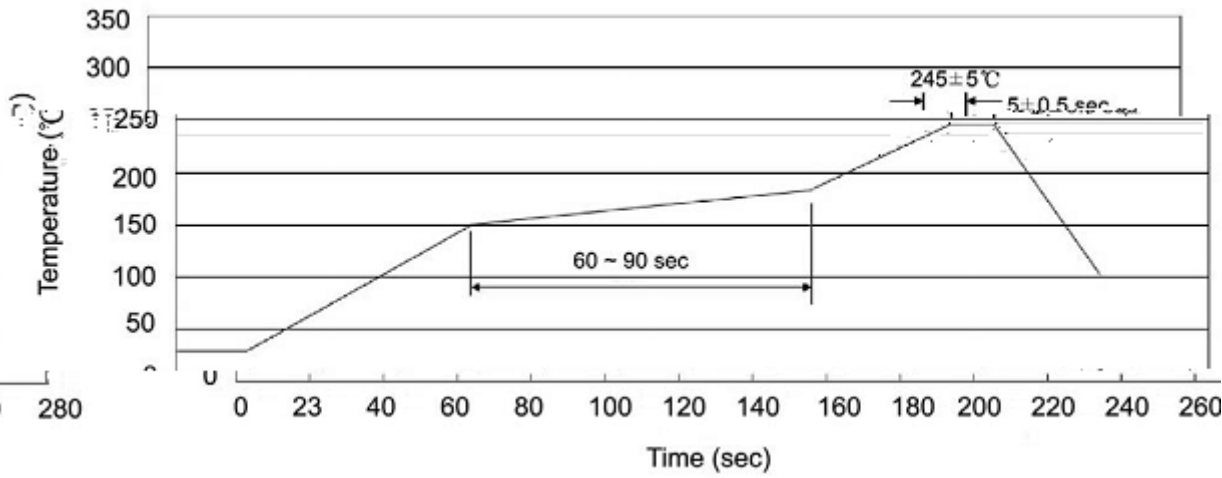
/ Marking Instructions



H

H

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



± ± ± ±

/ Resistance to Soldering Heat Test Conditions

± ± °C

/ Packaging SPEC.

封装形式	包装数量					包装尺寸		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOT-23	3,000	10	30,000	6	180,000	7 ×8	180×120×180	390×385×205

/ Notices